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ABSTRACT OF THE DISCLOSURE

SEMICONDUCTOR PACKAGING METHOD

The present invention relates to a semiconductor packaging method. The method comprises (S1) applying a die adhesive to an upper surface of a member through screen-printing; (S2) B-stage curing the member having the die adhesive; (S3) attaching a die on the B-stage cured die adhesive; (S4) wire-bonding the die to the member; and (S5) encapsulating the outside of the resultant, after the B-stage curing process of the step S2, a degree of cure of the die adhesive shows a decrease in heat capacity by 80 to 100%, and the step S3 is performed such that the die adhesive maintains an adhesive strength of 10 kgf/㎠ or more at normal temperature after the die attaching.

FIG. 1